

### 1. Global joint venture starts operations as WeEn Semiconductors

Dear customer.

As from November 9th, 2015 NXP Semiconductors N.V. and Beijing JianGuang Asset Management Co. Ltd established Bipolar Power joint venture (JV), **WeEn Semiconductors**, which will be used in future Bipolar Power documents together with new contact details.

In this document where the previous NXP references remain, please use the new links as shown below.

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Thank you for your cooperation and understanding,

WeEn Semiconductors



### DISCRETE SEMICONDUCTORS

## DATA SHEET

# BYW29EX series Rectifier diodes ultrafast, rugged

**Product specification** 

October 1998



NXP Semiconductors Product specification

### Rectifier diodes ultrafast, rugged

### **BYW29EX series**

### **GENERAL DESCRIPTION**

### **QUICK REFERENCE DATA**

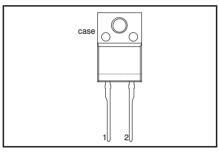
Glass passivated epitaxial rectifier diodes in a full pack plastic envelope, featuring low forward voltage drop, ultra-fast recovery times, soft recovery characteristic and guaranteed reverse surge and ESD capability. They are intended for use in switched mode power supplies and high frequency circuits in general where low conduction and switching losses are essential.

SYMBOL	PARAMETER	MAX.	MAX.	UNIT
$\begin{array}{c} V_{RRM} \\ V_{F} \\ I_{F(AV)} \\ t_{rr} \\ I_{RRM} \end{array}$	BYW29EX- Repetitive peak reverse voltage Forward voltage Forward current Reverse recovery time Repetitive peak reverse current	150 150 0.895 8 25 0.2	200 200 0.895 8 25 0.2	V V A ns A

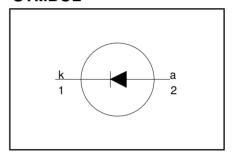
### **PINNING - SOD113**

PIN	DESCRIPTION			
1	cathode			
2	anode			
case	isolated			

### **PIN CONFIGURATION**



### **SYMBOL**



### **LIMITING VALUES**

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MA	AX.	UNIT
V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	Repetitive peak reverse voltage Crest working reverse voltage Continuous reverse voltage		1 1 1	<b>-150</b> 150 150 150	<b>-200</b> 200 200 200	\ \ \ \
I <sub>F(AV)</sub>	Average forward current <sup>1</sup>	square wave; $\delta$ = 0.5; $T_{hs} \le 106 ^{\circ}\text{C}$ sinusoidal; $a$ = 1.57;	-		8	A
	RMS forward current	T <sub>hs</sub> ≤ 109 °C	-		.3 I.3	A A
I <sub>F(RMS)</sub>		$t = 25 \mu s; \delta = 0.5;$ $T_{hs} \le 106  ^{\circ}C$	-		6	Ä
I <sub>FSM</sub>	Non-repetitive peak forward current	t = 10 ms t = 8.3 ms sinusoidal; with reapplied	-		80 88	A A
I <sup>2</sup> t I <sub>RRM</sub> I <sub>RSM</sub>	l <sup>2</sup> t for fusing Repetitive peak reverse current Non-repetitive peak reverse	$egin{array}{l} V_{\text{RWM}(\text{max})} \ t = 10 \ \text{ms} \ t_{\text{p}} = 2 \ \mu \text{s}; \ \delta = 0.001 \ t_{\text{p}} = 100 \ \mu \text{s} \ \end{array}$	- - -	0	.2 .2 .2	A <sup>2</sup> s A A
T <sub>stg</sub>	current   Storage temperature   Operating junction temperature		-40 -		50 50	.C

<sup>1</sup> Neglecting switching and reverse current losses

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Rectifier diodes ultrafast, rugged

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### **ESD LIMITING VALUE**

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>C</sub>	ı	Human body model; C = 250 pF; R = 1.5 kΩ	-	8	kV

### **ISOLATION LIMITING VALUE & CHARACTERISTIC**

T<sub>hs</sub> = 25 °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>isol</sub>	R.M.S. isolation voltage from both terminals to external heatsink	f = 50-60 Hz; sinusoidal waveform; R.H. ≤ 65%; clean and dustfree	ı		2500	>
C <sub>isol</sub>	Capacitance from both terminals to external heatsink	f = 1 MHz	-	10	1	pF

### THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th j-hs}$ $R_{th j-a}$	heatsink	with heatsink compound without heatsink compound in free air		- - 55	5.5 7.2 -	K/W K/W K/W

### **STATIC CHARACTERISTICS**

T<sub>i</sub> = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{F}$	Forward voltage	$I_F = 8 \text{ A}; T_i = 150^{\circ}\text{C}$	-	0.80	0.895	V
	_	$I_F = 8 A$	-	0.92	1.05	V
		$I_{\rm F} = 20 \text{ A}$	-	1.1	1.3	V
l <sub>R</sub>	Reverse current	$V_R = V_{RWM}$ ; $T_i = 100 ^{\circ}C$	-	0.2	0.6	mA
		$V_R = V_{RWM}$	-	2	10	μΑ

### **DYNAMIC CHARACTERISTICS**

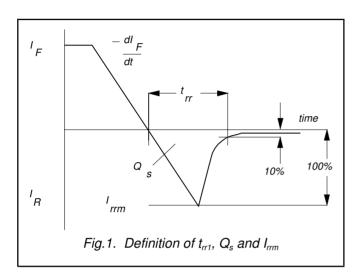
T<sub>i</sub> = 25 °C unless otherwise stated

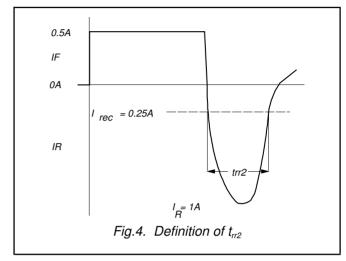
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Q <sub>s</sub>	Reverse recovery charge	$I_F = 2 \text{ A}; V_R \ge 30 \text{ V}; -dI_F/dt = 20 \text{ A}/\mu\text{s}$	-	4	11	nC
t <sub>rr1</sub>	Reverse recovery time	$I_F = 1 \text{ A}; V_R \ge 30 \text{ V};$ - $dI_F/dt = 100 \text{ A/}\mu\text{s}$	-	20	25	ns
$V_{\rm fr}$	Reverse recovery time Forward recovery voltage	$I_F = 0.5 \text{ A to } I_R = 1 \text{ A; } I_{rec} = 0.25 \text{ A}$ $I_E = 1 \text{ A; } dI_E/dt = 10 \text{ A/}\mu\text{s}$	-	15 1	20 -	ns V

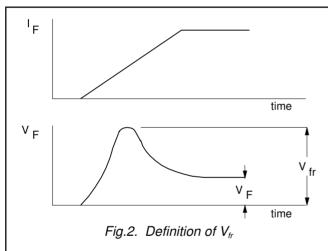
NXP Semiconductors Product specification

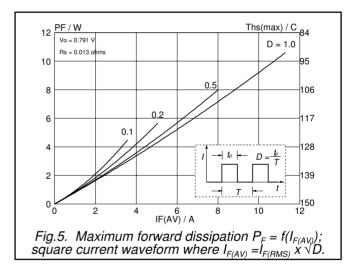
### Rectifier diodes ultrafast, rugged

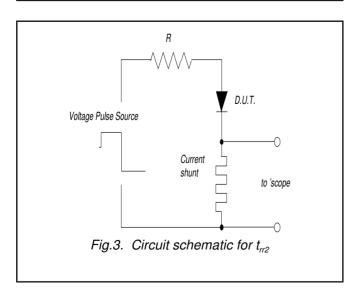
### BYW29EX series











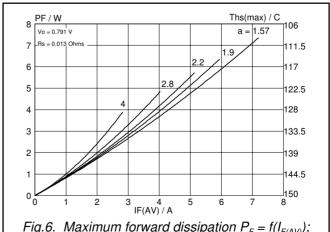
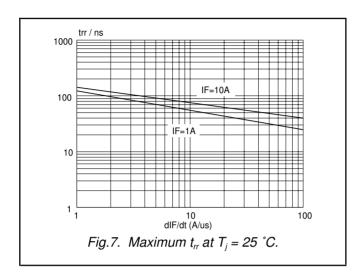
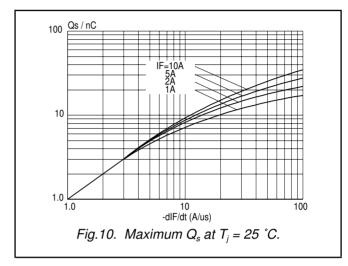


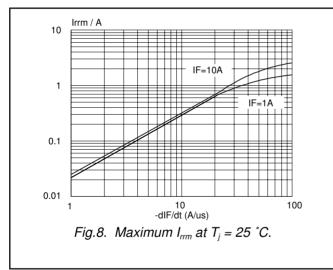
Fig.6. Maximum forward dissipation  $P_F = f(I_{F(AV)})$ ; sinusoidal current waveform where a = form factor  $= I_{F(RMS)} / I_{F(AV)}$ .

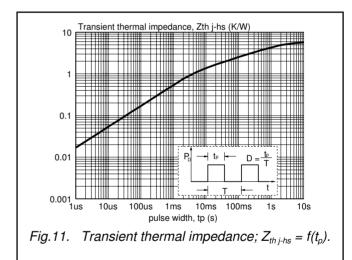
### Rectifier diodes ultrafast, rugged

### BYW29EX series









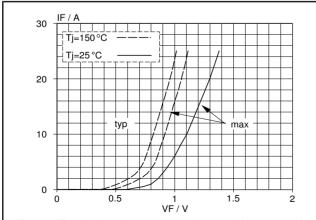
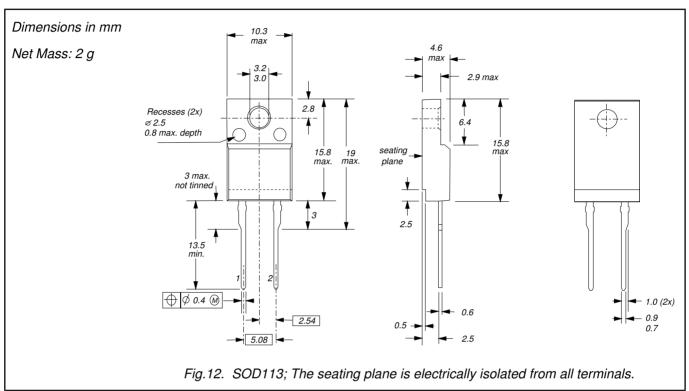


Fig.9. Typical and maximum forward characteristic  $I_F = f(V_F)$ ; parameter  $T_j$ 

**NXP Semiconductors** Product specification

Rectifier diodes ultrafast, rugged BYW29EX series

### **MECHANICAL DATA**



### **Notes**

- Refer to mounting instructions for F-pack envelopes.
   Epoxy meets UL94 V0 at 1/8".

### Legal information

#### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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### **Contact information**

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